

HLT2000 and HLT3500 Thermally Conductive Gel

BENEFITS AND FEATURES

- Low contact resistance
- Easy to dispense and rework
- High compressibility for low stress applications
- Long-term reliability
- Less oil separation
- No pump out and cracking

OVERVIEW

Honeywell HLT2000 and HLT3500 are two-part, dispensable thermally conductive gel, which offer long-term reliability and superior softness. The enhanced bonding force between the polymer base and the filler largely improves the thermally conductive gel oil separation issue in storage. Prior to curing, the material maintains good thixotropic characteristics and low viscosity to be easily dispensed. The product can be cured in short time after two-component mixing at room temperature. The high compressibility minimizes thermal resistance at interfaces, while maintaining excellent performance during reliability testing.



TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory & power modules

STORAGE & USE

- Shelf Life 6 months at 23°C±2°C

Property		HLT2000	HLT3500	Test Method
Specific Gravity		2.8	3.2	ASTM D792
Viscosity (cps@25°C)		200,000~350,000	300,000~450,000	ASTM D2196 (Brookfield Viscometer, #7 spindle, 10rpm)
Hardness (Shore00)		50	50	ASTM D2240
Thermal Conductivity (W/m·K)		2.0	3.5	ASTM D5470
Thermal Impedance (°C·in ² /W) (1mm@10psi) (Typical Value)		0.66	0.44	ASTM D5470
Cure Schedule	25°C (hr)	10	12	
	100°C (min)	30	30	
Color		Part A: Yellow Part B: White	Part A: White Part B: Blue	Visual

Honeywell Electronic Materials

USA: 1-509-252-2102
China: 400-840-2233
Germany: 49-5137-999-9199
Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
Singapore: 65-6580-3593
www.electronicmaterials.com

Although all statements and information contained herein are believed to be accurate and reliable, they are presented without guarantee or warranty of any kind, express or implied. Information provided herein does not relieve the user from the responsibility of carrying out its own tests and experiments, and the user assumes all risks and liability for use of the information and results obtained. Statements or suggestions concerning the use of materials and processes are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should not assume that all toxicity data and safety measures are indicated herein or that other measures may not be required.